# September 2006 Advance Information



### 3.3V 128K X 8 CMOS SRAM (Center power and ground)

#### **Features**

- Industrial and commercial temperatures
- Organization: 131,072 x 8 bits
- High speed
- 10 ns address access time
- 5 ns output enable access time
- Low power consumption via ship deselect
- Easy memory expansion with  $\overline{CE}$ ,  $\overline{OE}$  inputs
- Center power and ground
- TTL/LVTTL-compatible, three-state I/O
- JEDEC-standard packages

- 32-pin, 300 mil SOJ
- 32-pin, 400 mil SOJ
- 32-pin, TSOP 2
- ESD protection  $\geq 2000$  volts

### **Pin arrangement**

## Logic block diagram



02 pin	100	<i>/ L</i>
A0 1 A1 2 A2 3 A2 1 I 0 I 2 A2 A2 1 I 0 I 0 I 1 A A I 1 A I 2 A A I 1 I 2 A A I 1 I 2 A A I 1 I 5 I/00 1 I 7 V <sub>CC</sub> B GND 1 I 1 I 1 V <sub>CC</sub> B GND 1 I 1 I 1 I 1 I 1 I 1 I 1 I 1 I	AS7C31025C	32         A16           31         A15           30         A14           28         OE           27         I/O7           28         OE           27         I/O7           24         VCC           23         I/O4           21         A12           22         I/O4           21         A12           20         A11           18         A9           17         A8
32-pin S0           32-pin S0           32-pin S1           A1           A2           A3           A3           A2           B32           A3           A3           A3           A3           A3           A3           A3           A3           A4           CE           JO0           JO0           JO0           JO0           JO2           JO2           JO2           JO3           JO3           JO3           JO3           JO3           JO4           JO4           JO3           JO3           JO3           JO4           JO4           JO4           JO5           JO5  <	AS7C31025C	300 mil)           32         A16           31         A15           30         A14           29         A13           28         OE           27         I/O6           25         I/O2           24         I/O5           22         I/O4           23         I/O5           23         I/O5           23         I/O5           24         A12           21         A12           20         A11           19         A10           18         A9           17         A8

32-pin TSOP 2



#### **Functional description**

The AS7C31025C is 3V a high-performance CMOS 1,048,576-bit Static Random Access Memory (SRAM) device organized as 131,072 x 8 bits. It is designed for memory applications where fast data access, low power, and simple interfacing are desired.

Equal address access and cycle times ( $t_{AA}$ ,  $t_{RC}$ ,  $t_{WC}$ ) of 10 ns with output enable access times ( $t_{OE}$ ) of 5 ns are ideal for high-performance applications. The chip enable input  $\overline{CE}$  permits easy memory and expansion with multiple-bank memory systems.

When  $\overline{CE}$  is high the device enters standby mode. A write cycle is accomplished by asserting write enable ( $\overline{WE}$ ) and chip enable ( $\overline{CE}$ ). Data on the input pins I/O0 through I/O7 is written on the rising edge of  $\overline{WE}$  (write cycle 1) or  $\overline{CE}$  (write cycle 2). To avoid bus contention, external devices should drive I/O pins only after outputs have been disabled with output enable ( $\overline{OE}$ ) or write enable ( $\overline{WE}$ ).

A read cycle is accomplished by asserting output enable ( $\overline{OE}$ ) and chip enable ( $\overline{CE}$ ), with write enable ( $\overline{WE}$ ) high. The chip drives I/O pins with the data word referenced by the input address. When either chip enable or output enable is inactive or write enable is active, output drivers stay in high-impedance mode.

All chip inputs and outputs are TTL-compatible, and operation is from a single 3.3 V supply. The AS7C31025C is packaged in common industry standard packages.

Parameter	Symbol	Min	Max	Unit
Voltage on V <sub>CC</sub> relative to GND	V <sub>t1</sub>	-0.50	+4.6	V
Voltage on any pin relative to GND	V <sub>t2</sub>	-0.50	V <sub>CC</sub> + 0.5	V
Power dissipation	P <sub>D</sub>	_	1.25	W
Storage temperature (plastic)	T <sub>stg</sub>	-55	+125	° C
Ambient temperature with V <sub>CC</sub> applied	T <sub>bias</sub>	-55	+125	° C
DC current into outputs (low)	I <sub>OUT</sub>	-	50	mA

#### Absolute maximum ratings

NOTE: Stresses greater than those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions outside those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

#### **Truth table**

CE	WE	OE	Data	Mode
Н	Х	Х	High Z	Standby (I <sub>SB</sub> , I <sub>SB1</sub> )
L	Н	Н	High Z	Output disable (I <sub>CC</sub> )
L	Н	L	D <sub>OUT</sub>	Read (I <sub>CC</sub> )
L	L	Х	D <sub>IN</sub>	Write (I <sub>CC</sub> )

Key: X = don't care, L = low, H = high.



### **Recommended operating conditions**

Parameter	Symbol	Min	Nominal	Max	Unit
Supply voltage	V <sub>CC</sub>	3.0	3.3	3.6	V
Input voltage	V <sub>IH</sub>	2.0	_	V <sub>CC</sub> + 0.3	V
input voltage	V <sub>IL</sub>	-0.5	_	0.8	V
Ambient operating temperature (Industrial)	T <sub>A</sub>	-40	_	85	° C

$$\label{eq:VIL} \begin{split} &V_{IL}\ min = -2.0V\ for\ pulse\ width\ less\ than\ 5ns,\ once\ per\ cycle.\\ &V_{IH}\ min = -V_{CC} + 2.0V\ for\ pulse\ width\ less\ than\ 5ns,\ once\ per\ cycle. \end{split}$$

#### DC operating characteristics (over the operating range) $^{I}$

			AS7C31	025C-10	
Parameter	Sym	Test conditions	Min	Max	Unit
Input leakage current	I <sub>LI</sub>	$V_{CC} = Max, V_{IN} = GND$ to $V_{CC}$	-	5	μΑ
Output leakage current	I <sub>LO</sub>	$V_{CC} = Max, \overline{CE} = V_{IH},$ $V_{out} = GND \text{ to } V_{CC}$	_	5	μΑ
Operating power supply current	I <sub>CC</sub>	$V_{CC} = Max$ $\overline{CE} \le V_{IL}, f = f_{Max},$ $I_{OUT} = 0 \text{ mA}$	_	150	mA
	I <sub>SB</sub>	$V_{CC} = Max$ $\overline{CE} \ge V_{IH}, f = f_{Max}$	_	50	mA
Standby power supply current <sup>1</sup>	I <sub>SB1</sub>	$\begin{split} V_{CC} &= Max, \ \overline{CE} \geq V_{CC} - 0.2 \ V, \\ V_{IN} \leq 0.2 \ V \ or \ V_{IN} \geq V_{CC} - 0.2 \ V, \\ f &= 0 \end{split}$	_	10	mA
Output voltage	V <sub>OL</sub>	$I_{OL} = 8 \text{ mA}, V_{CC} = Min$	_	0.4	V
Supur foruge	V <sub>OH</sub>	$I_{OH} = -4 \text{ mA}, V_{CC} = Min$	2.4	_	V

### **Capacitance** $(f = 1 \text{ MHz}, T_a = 25^{\circ} \text{ C}, V_{CC} = \text{NOMINAL})^2$

Parameter	Symbol	Signals	Test conditions	Max	Unit
Input capacitance	C <sub>IN</sub>	A, $\overline{CE}$ , $\overline{WE}$ , $\overline{OE}$	$V_{IN} = 3dV$	6	pF
I/O capacitance	C <sub>I/O</sub>	I/O	$V_{OUT} = 3dV$	7	pF

Note:

1. This parameter is guaranteed by device characterization, but is not production tested.



### Read cycle (over the operating range)<sup>3,9</sup>

		AS7C31	.025C-10		
Parameter	Symbol	Min	Max	Unit	Notes
Read cycle time	t <sub>RC</sub>	10	-	ns	
Address access time	t <sub>AA</sub>	_	10	ns	3
Chip enable $(\overline{CE})$ access time	t <sub>ACE</sub>	_	10	ns	3
Output enable $(\overline{OE})$ access time	t <sub>OE</sub>	_	5	ns	
Output hold from address change	t <sub>OH</sub>	4	_	ns	5
$\overline{CE}$ low to output in low Z	t <sub>CLZ</sub>	4	-	ns	4, 5
CE high to output in high Z	t <sub>CHZ</sub>	0	5	ns	4, 5
OE low to output in low Z	t <sub>OLZ</sub>	0	_	ns	4, 5
OE high to output in high Z	t <sub>OHZ</sub>	0	5	ns	4, 5
Power up time	t <sub>PU</sub>	0	—	ns	4, 5
Power down time	t <sub>PD</sub>	_	10	ns	4, 5

### Key to switching waveforms

**Rising input** 

Falling input

Undefined/don't care

## Read waveform 1 (address controlled)<sup>3,6,7,9</sup>



## Read waveform 2 (CE and OE controlled)<sup>3,6,8,9</sup>





### Write cycle (over the operating range)<sup>11</sup>

	AS7C31025C-10		025C-10		
Parameter	Symbol	Min	Max	Unit	Notes
Write cycle time	t <sub>WC</sub>	10	_	ns	
Chip enable $(\overline{CE})$ to write end	t <sub>CW</sub>	7	-	ns	
Address setup to write end	t <sub>AW</sub>	7	—	ns	
Address setup time	t <sub>AS</sub>	0	_	ns	
Write pulse width	t <sub>WP</sub>	7	-	ns	
Write recovery time	t <sub>WR</sub>	0	—	ns	
Address hold from end of write	t <sub>AH</sub>	0	_	ns	
Data valid to write end	t <sub>DW</sub>	5	-	ns	
Data hold time	t <sub>DH</sub>	0	—	ns	4, 5
Write enable to output in high Z	t <sub>WZ</sub>	0	5	ns	4, 5
Output active from write end	t <sub>OW</sub>	3	_	ns	4, 5

# Write waveform 1 (WE controlled)<sup>10,11</sup>



# Write waveform 2 (CE controlled)<sup>10,11</sup>



## AS7C31025C



#### **AC test conditions**

- Output load: see Figure B.
- Input pulse level: GND to 3.0 V. See Figure A.
- Input rise and fall times: 3 ns. See Figure A.
- Input and output timing reference levels: 1.5 V.





#### Notes

- 1 During  $V_{CC}$  power-up, a pull-up resistor to  $V_{CC}$  on  $\overline{CE}$  is required to meet  $I_{SB}$  specification.
- 2 This parameter is sampled, but not 100% tested.
- 3 For test conditions, see *AC Test Conditions*, Figures A and B.
- $4 t_{CLZ}$  and  $t_{CHZ}$  are specified with CL = 5 pF, as in Figure B. Transition is measured  $\pm 200 \text{ mV}$  from steady-state voltage.
- 5 This parameter is guaranteed, but not 100% tested.
- $\overline{\text{WE}}$  is high for read cycle.
- 7  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$  are low for read cycle.
- 8 Address is valid prior to or coincident with  $\overline{\text{CE}}$  transition low.
- 9 All read cycle timings are referenced from the last valid address to the first transitioning address.
- 10 N/A
- 11 All write cycle timings are referenced from the last valid address to the first transitioning address.
- 12 N/A.
- 13 C = 30 pF, except all high Z and low Z parameters where C = 5 pF.



## **Package dimensions**



	32-pin TSO	<b>OP 2 (mm)</b>		
Symbol	Min	Max		
Α	-	1.20		
A1	0.05	0.15		
b	0.3	0.52		
С	0.12	0.21		
D	20.82	21.08		
<b>E</b> 1	10.03	10.29		
E	11.56	11.96		
е	1.27	BSC		
L	0.40	0.60		
ZD	0.95 REF.			
α	0°	5°		





	32-pin 300	n SOJ mil	32-pin 400	n SOJ mil
Symbol	Min	Max	Min	Max
Α	0.128	0.145	0.132	0.146
A1	0.025	-	0.025	-
A2	0.095	0.105	0.105	0.115
В	0.026	0.032	0.026	0.032
b	0.016	0.020	0.015	0.020
С	0.007	0.010	0.007	0.013
D	0.820	0.830	0.820	0.830
E	0.255	0.275	0.354	0.378
<b>E1</b>	0.295	0.305	0.395	0.405
<b>E2</b>	0.330	0.340	0.435	0.445
e	0.050	BSC	0.050	BSC



## **Ordering Codes**

Package	Volt/Temperature	<b>10 ns</b>
300-mil SOJ	5V Industrial	AS7C31025C-10TJIN
400-mil SOJ	5V Industrial	AS7C31025C-10JIN
TSOP 2	5V Industrial	AS7C31025C-10TIN

# Part numbering system

AS7C	X	1025B	-XX	X	X	X
SRAM prefix	Voltage: 3 = 3.3 V CMOS	Device number	Access time	Package: TJ = SOJ 300  mil J = SOJ 400  mil T = TSOP2	Temperature range I = industrial, -40° C to 85° C	N = Lead Free Part



Alliance Memory, Inc. 1116 South Amphlett San Mateo, CA 94402 Tel: 650-525-3737 Fax: 650-525-0449

www.alliancememory.com

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